WHAT IS CLAIMED IS:

1. A package carrier comprising

multiple ceramic substrates where each ceramic substrate is composed of multiple small low-temperature co-fired ceramics (LTCC) ceramic plates with wire patterns; and

a frame having a bottom, at least one side, multiple through holes, multiple cutting channels defined between two of the through holes, at least one reference hole defined on the at least one side and a polymide tape attached to the bottom to make the through holes become recess to hold the ceramic substrates, wherein the polymide tape has a high temperature-resistance.

2. The package carrier as claimed in claim 1, wherein the frame is made of plastic material.

3. The package carrier as claimed in claim 1, wherein the ceramic substrates and through holes are rectangular, and the ceramic substrates are slightly smaller than the through holes.

4. The package carrier as claimed in claim 3, wherein each through hole has four corners in which four notches are respectively defined.